

2SK1968 Silicon N Channel MOS FET

REJ03G0989-0200 (Previous: ADE-208-1337) Rev.2.00 Sep 07, 2005

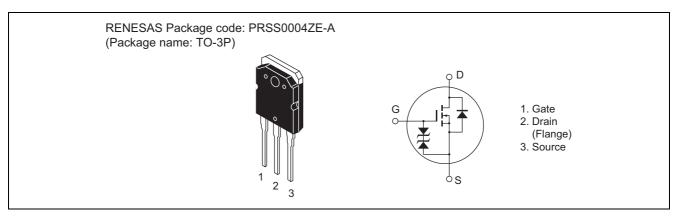
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- No secondary breakdown
- Suitable for switching regulator
- Low drive current

Outline





Absolute Maximum Ratings

			(1a - 25 C)
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	600	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	ID	12	A
Drain peak current	I _{D(pulse)} * ¹	48	A
Body to drain diode reverse drain current	I _{DR}	12	A
Channel dissipation	Pch* ²	100	W
Channel temperature	Tch	150	С°
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = $25^{\circ}C$

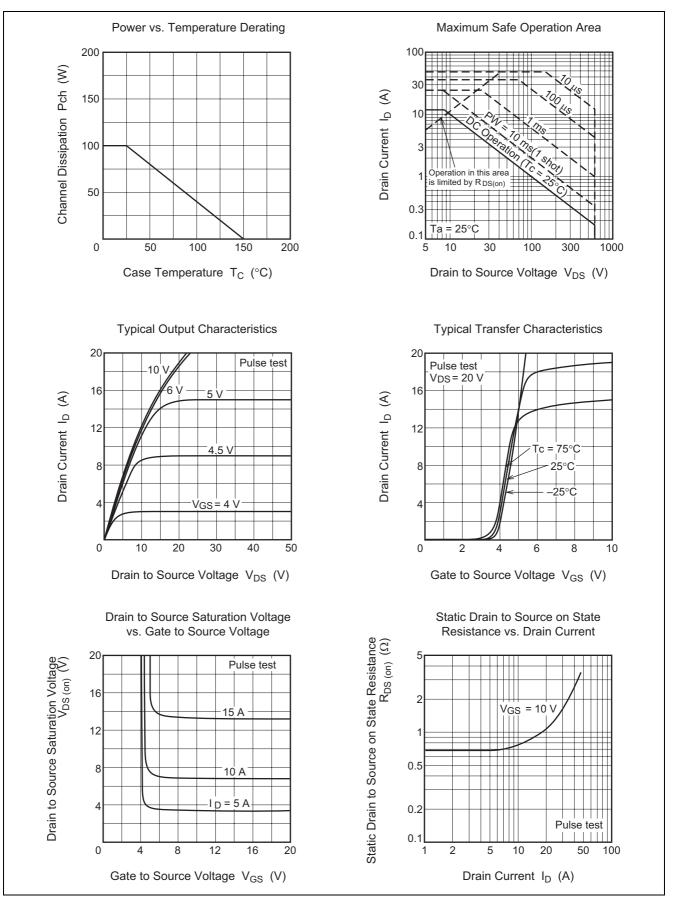
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±30	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	—	±10	μΑ	$V_{GS} = \pm 25 V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	250	μΑ	$V_{DS} = 500 \text{ V}, \text{ V}_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	2.0	_	3.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state	R _{DS(on)}		0.68	0.88	Ω	$I_D = 6 A, V_{GS} = 10 V^{*3}$
resistance						
Forward transfer admittance	y _{fs}	5	10	—	S	$I_D = 6 A, V_{DS} = 10 V^{*3}$
Input capacitance	Ciss	_	1800	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 MHz
Output capacitance	Coss	—	400	—	pF	
Reverse transfer capacitance	Crss	_	60	—	pF	
Turn-on delay time	t _{d(on)}	_	25	_	ns	$I_D = 6 A, V_{GS} = 10 V,$
Rise time	tr		70		ns	$R_L = 5 \Omega$
Turn-off delay time	t _{d(off)}		145	_	ns	
Fall time	t _f		65		ns	
Body to drain diode forward voltage	V _{DF}		1.1	_	V	$I_F = 12 \text{ A}, V_{GS} = 0$
Body to drain diode reverse	t _{rr}		670	_	ns	$I_F = 12 \text{ A}, V_{GS} = 0,$
recovery time						$di_F/dt = 100 \text{ A}/\mu \text{s}$

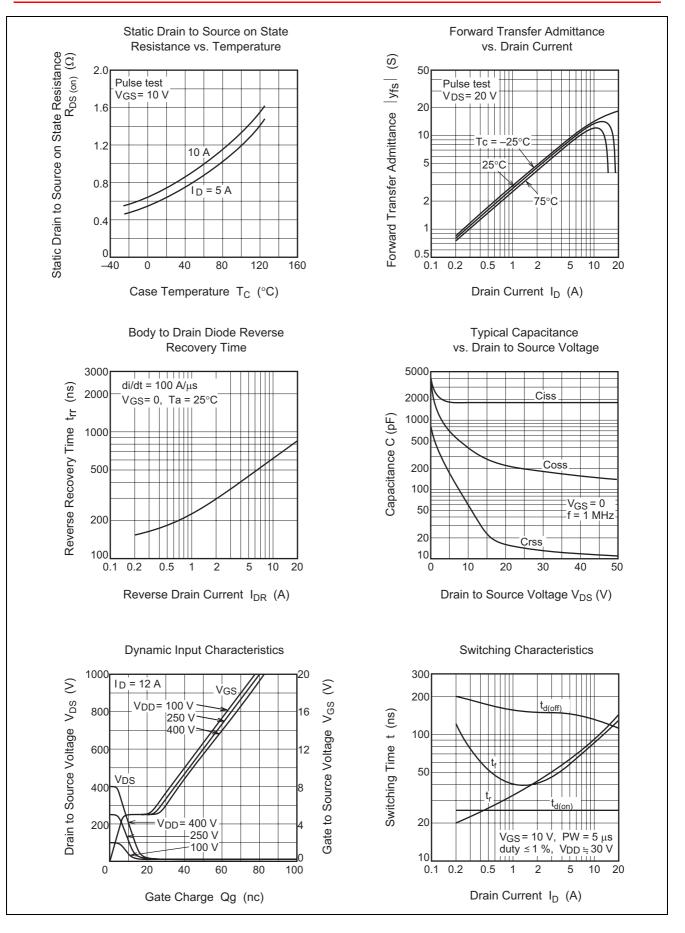
Note: 3. Pulse Test



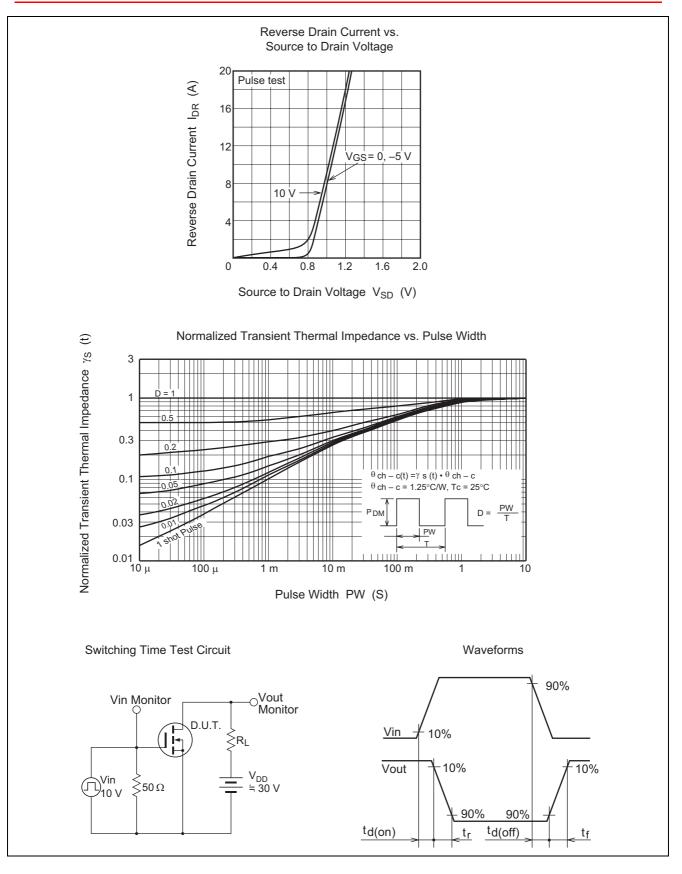
Main Characteristics





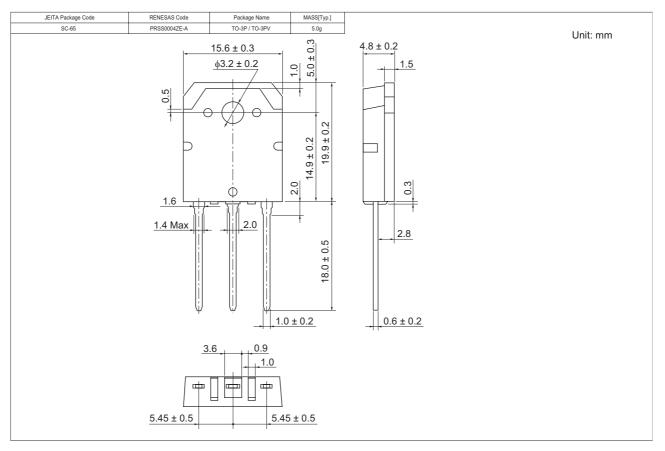






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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK1968-E	360 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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